

TM

BZT52B4V3S THRU BZT52B39S

**200 mW
Zener Diode
4.3 to 39 Volts**

Features

- Planar Die Construction
- 200mW Power Dissipation on Ceramic PCB
- General Purpose Medium Current
- Ideally Suited for Automated Assembly Processes
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0 and MSL Rating 1
- Lead Free Finish/RoHS Compliant("P" Suffix designates RoHS Compliant. See ordering information)

Absolute Maximum Ratings

Symbol	Parameter	Rating	Unit
P _D	Power dissipation	200	mW
T _J	Junction Temperature	-65 to +175	°C
T _{STG}	Storage Temperature Range	-65 to +175	°C

Absolute Maximum Ratings

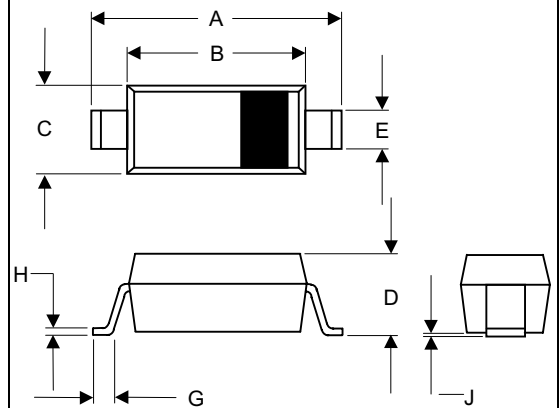
Symbol	Parameter	Rating	Unit
R _{thJA}	Thermal Resistance Junction to Ambient*	305	°C/W

* Device mounted on ceramic PCB: 7.6mm x 9.4mm x 0.87mm with pad areas 25 mm²

Electrical Characteristics

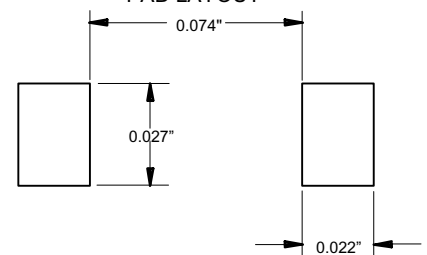
Symbol	Parameter	Rating	Unit
V _F	Maximum Forward Voltage (I _F =10mA _{dc})	0.9	V

SOD-323



DIM	DIMENSIONS				NOTE
	INCHES		MM		
	MIN	MAX	MIN	MAX	
A	.090	.107	2.30	2.70	
B	.063	.071	1.60	1.80	
C	.045	.053	1.15	1.35	
D	.031	.045	0.80	1.15	
E	.010	.016	0.25	0.40	
G	.004	.018	0.10	0.45	
H	.004	.010	0.10	0.25	
J	-----	.006	-----	0.15	

SUGGESTED SOLDER PAD LAYOUT



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Electrical Characteristics@25°C

Type	ZENER VOLTAGE $V_Z^{(1)}$ VOLTS			Maximum Zener Impedance ⁽²⁾ Z_{ZT} (OHMS)		Maximum Zener Impedance ⁽²⁾ Z_{ZK} (OHMS)		REVERSE CURRENT $I_R(\text{Max})@V_R$		Typical Temperature Coefficient @ I_{ZTC}		Marking
	Min	Nom	Max	I_{ZT} (mA)	Max	I_{ZK} (mA)	Max	μA	V	$\text{mV}/^\circ\text{C}$		
BZT52B4V3S	4.21	4.3	4.39	5	90	1	600	3	1	-3.5	0	W7
BZT52B4V7S	4.61	4.7	4.79	5	80	1	500	3	2	-3.5	0.2	W8
BZT52B5V1S	5.0	5.1	5.2	5	60	1	480	2	2	-2.7	1.2	W9
BZT52B5V6S	5.49	5.6	5.71	5	40	1	400	1	2	-2	2.5	WA
BZT52B6V2S	6.08	6.2	6.32	5	10	1	150	3	4	0.4	3.7	WB
BZT52B6V8S	6.66	6.8	6.94	5	15	1	80	2	4	1.2	4.5	WC
BZT52B7V5S	7.35	7.5	7.65	5	15	1	80	1	5	2.5	5.3	WD
BZT52B8V2S	8.04	8.2	8.36	5	15	1	80	0.7	5	3.2	6.2	WE
BZT52B9V1S	8.92	9.1	9.28	5	15	1	100	0.5	6	3.8	7	WF
BZT52B10S	9.8	10	10.2	5	20	1	150	0.2	7	4.5	8	WG
BZT52B11S	10.78	11	11.22	5	20	1	150	0.1	8	5.4	9	WH
BZT52B12S	11.76	12	12.24	5	25	1	150	0.1	8	6	10	WI
BZT52B13S	12.74	13	13.3	5	30	1	170	0.1	8	7	11	WK
BZT52B15S	14.7	15	15.3	5	30	1	200	0.1	10.5	9.2	13	WL
BZT52B16S	15.68	16	16.3	5	40	1	200	0.1	11.2	10.4	14	WM
BZT52B18S	17.6	18	18.4	5	45	1	225	0.1	12.6	12.4	16	WN
BZT52B20S	19.6	20	20.4	5	55	1	225	0.1	14	14.4	18	WO
BZT52B22S	21.56	22	22.44	5	55	1	250	0.1	15.4	16.4	20	WP
BZT52B24S	23.52	24	24.5	5	70	1	250	0.1	16.8	18.4	22	WR
BZT52B27S	26.46	27	27.54	2	80	0.5	300	0.1	18.9	21.4	25.3	WS
BZT52B30S	29.4	30	30.6	2	80	0.5	300	0.1	21	24.4	29.4	WT
BZT52B33S	32.34	33	33.7	2	80	0.5	325	0.1	23.1	27.4	33.4	WU
BZT52B36S	35.28	36	36.72	2	90	0.5	350	0.1	25.2	30.4	37.4	WW
BZT52B39S	38.22	39	39.8	2	130	0.5	350	0.1	27.3	33.4	41.2	WX

(1) Device mounted on ceramic PCB: 7.6mm x 9.4mm x 0.87mm with pad areas 25 mm²

(2) f=1KHz

Ordering Information

Device	Packing
(Part Number)-TP	Tape&Reel;3Kpcs/Reel